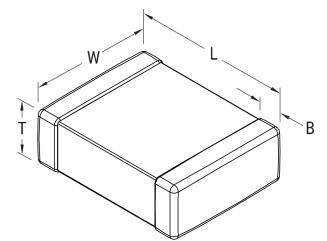


CKC33C223MEGAC7210

KC-LINK Comm COG, Ceramic, 0.022 uF, 20%, 1200 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

Dimensions		
Chip Size	3640	
L	9.3mm +/-0.6mm	
W	10.2mm +/-0.4mm	
Т	2.5mm +/-0.20mm	
В	1.27mm +/-0.4mm	

Packaging Specifications	
n, Plastic Tape	

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.06 g
Shelf Life	78 Weeks
MSL	1

Specifications			
Capacitance	0.022 uF		
Measurement Condition	1 kHz 1.0Vrms		
Capacitance Tolerance	20%		
Voltage DC	1200 VDC		
Dielectric Withstanding Voltage	1440 VDC		
Temperature Range	-55/+150°C		
Temperature Coefficient	COG		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour		
Insulation Resistance	45.4545 GOhms		

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